

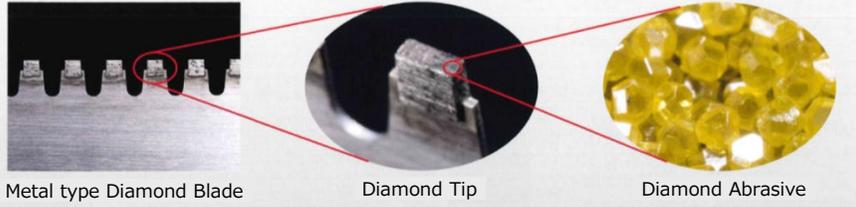


With metal-bonded diamond chips

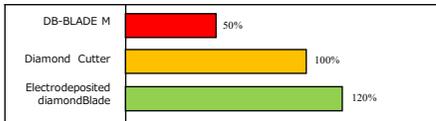
Proprietary DBSAW series blade

Diamond band saw blade

# DB-BLADE M

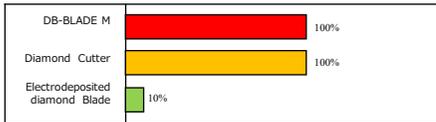


Processing time at  $\phi 300$  quartz glass cutting  
(Assume 100% diamond cutter)



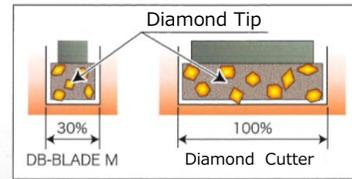
※Internal comparison

Blade life when cutting  $\phi 300$  quartz glass  
(Assume 100% diamond cutter)



※Internal comparison

Comparison of Switching When Cutting  $\phi 300$  Quartz Glass  
(Assume 100% diamond cutter)



※Internal comparison

Compatible machines	Size	Pitch	Ship size	Chip thickness
DBSAW500	125x0.8x5410	10	3x3	1.5 1.8
CBSAW1000	155x1.25x9730	10	3x3	2.5

(in mm)

※Chip thickness(Mesh) :1.5 (#50/60) 1.8 (#100/120)

Mesh (average particle size)	Recommended work material (example)
#50/60(300 $\mu$ m)	Quartz glass optical glass ceramics (raw material) carbon
#100/120(149 $\mu$ m)	Ceramic (sintered) Silicon sapphire

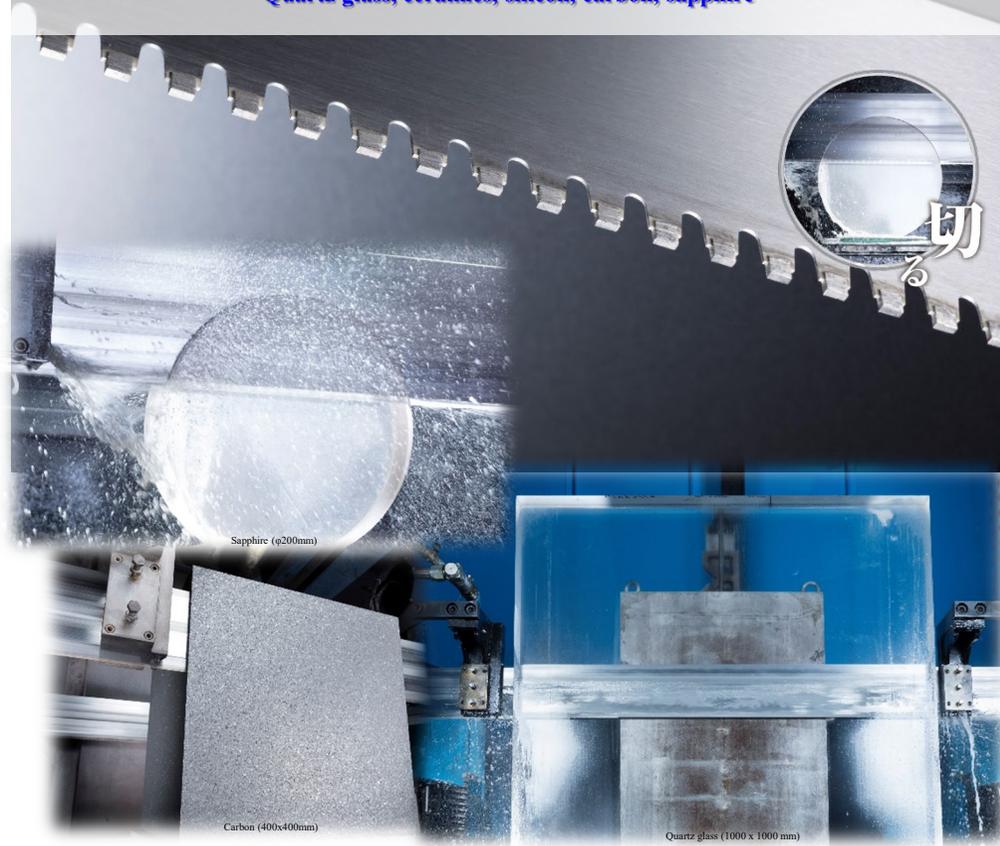
※"#50/60" for early cutting. "#100/120" for minimizing missing workpieces

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# Cutting of rigid brittle material

Quartz glass, ceramics, silicon, carbon, sapphire



Applicable materials (example)

